

# Laser Trimming Tool

**LTT-250** Laser Ablation and Excision tool for non-contact drilling and milling of technical polymers and medical products.



## KEY FEATURES

- ❖ Clean removal of polymer layers by ablation
- ❖ No damage to metallization or substrate
- ❖ PC selection of ablation motif
- ❖ Motorized X,Y,Z axes for 3D packaging
- ❖ Auto switch from ablation>excision mode
- ❖ Auto align to fiducials
- ❖ CAD compatible
- ❖ Efficient fume extraction
- ❖ Easy to use

## APPLICATIONS

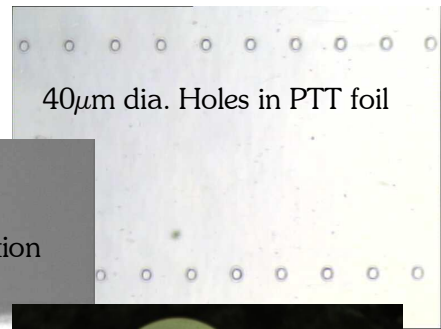
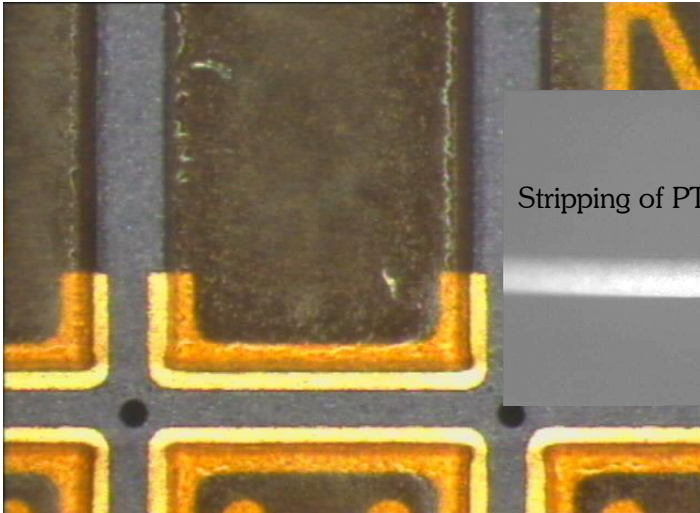
- ❖ Trimming of electronics packaging/contact clean,
- ❖ Milling/drilling of a wide range of polymers & composites
- ❖ Tablet drilling

**OPTEC**  
laser micromachining systems

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APPLICATIONS EXAMPLES

Selective removal of dielectric from ceramic & Au pads



Tablet drilling (OROS)

MACHINE SPECIFICATIONS

*Laser Type:-*

*Operating Wavelength*

*Pulse Energy*

*Repetition rate*

*On-target e.d.*

*Motifs*

*Part Holding*

*Environment*

*X,Y machining area*

*Speed/position resolution*

*Theta stage option*

*Focus depth/part height(Z axis)*

*CCTV inspection*

*Control software*

*CO<sub>2</sub> Light Machinery TEA GSIL Impact 2000 series SSM*

*9.3µm*

*400mJ-4J*

*150Hz-15Hz*

*4-16J/cm<sup>2</sup>(ablation); >50J/cm<sup>2</sup>(excision), auto-change*

*Up to 2mm in static mode, user choice on 15 pos. selector, or up to 10x10mm in scanning mode(option)*

*Vacuum chuck and/or wafer clamps*

*Fume extractor/filter*

*300\*300mm(larger sizes available on option)*

*30mm/s, 1µm(fast linear drive stages available on option)*

*360° full rotation or +/-3° auto-trim stage options*

*25mm*

*Offset déttented zoom, 45-300X; image acquisition*

*ProcessPower multi-level access, user-friendly interface with set-up & CAD conversion routines, auto-align functions and video measuring cursor*

